

TC74HCT273AP, TC74HCT273AF, TC74HCT273AFW

Octal D-Type Flip Flop with Clear

The TC74HCT273A is a high speed CMOS OCTAL D-TYPE FLIP FLOP fabricated with silicon gate C²MOS technology.

It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

Their inputs are compatible with TTL, NMOS, and CMOS output voltage levels.

Information signals applied to D inputs are transferred to the Q outputs on the positive going edge of the clock pulse.

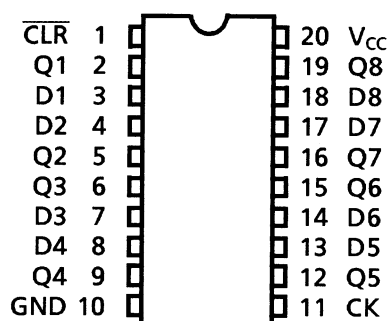
When the CLR input is held "L", the Q outputs are at a low logic level independent of the other inputs.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

Features

- High speed: $f_{\max} = 90 \text{ MHz}$ (typ.) at $V_{CC} = 5 \text{ V}$
- Low power dissipation: $I_{CC} = 4 \mu\text{A}$ (max) at $T_a = 25^\circ\text{C}$
- Compatible with TTL outputs: $V_{IH} = 2.0 \text{ V}$ (min)
 $V_{IL} = 0.8 \text{ V}$ (max)
- Wide interfacing ability: LSTTL, NMOS, CMOS
- Output drive capability: 10 LSTTL loads
- Symmetrical output impedance: $|I_{OH}| = I_{OL} = 4 \text{ mA}$ (min)
- Balanced propagation delays: $t_{pLH} \approx t_{pHL}$
- Pin and function compatible with 74LS273

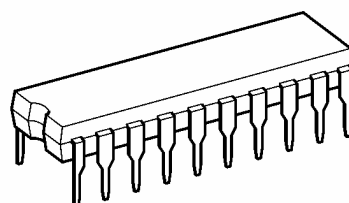
Pin Assignment



(TOP VIEW)

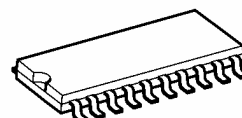
Note: xxxFW (JEDEC SOP) is not available in Japan.

TC74HCT273AP

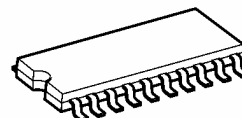


DIP20-P-300-2.54A

TC74HCT273AF

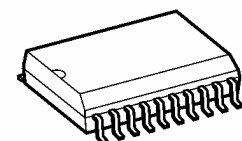


SOP20-P-300-1.27A



SOP20-P-300-1.27

TC74HCT273AFW

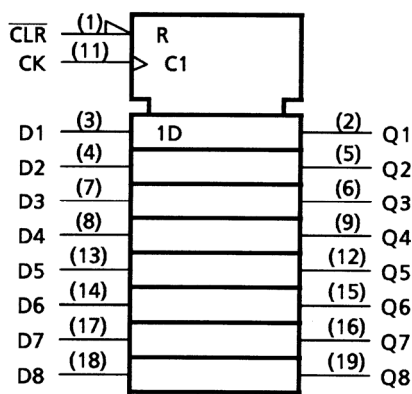


SOL20-P-300-1.27

Weight

DIP20-P-300-2.54A	: 1.30 g (typ.)
SOP20-P-300-1.27A	: 0.22 g (typ.)
SOP20-P-300-1.27	: 0.22 g (typ.)
SOL20-P-300-1.27	: 0.46 g (typ.)

IEC Logic Symbol

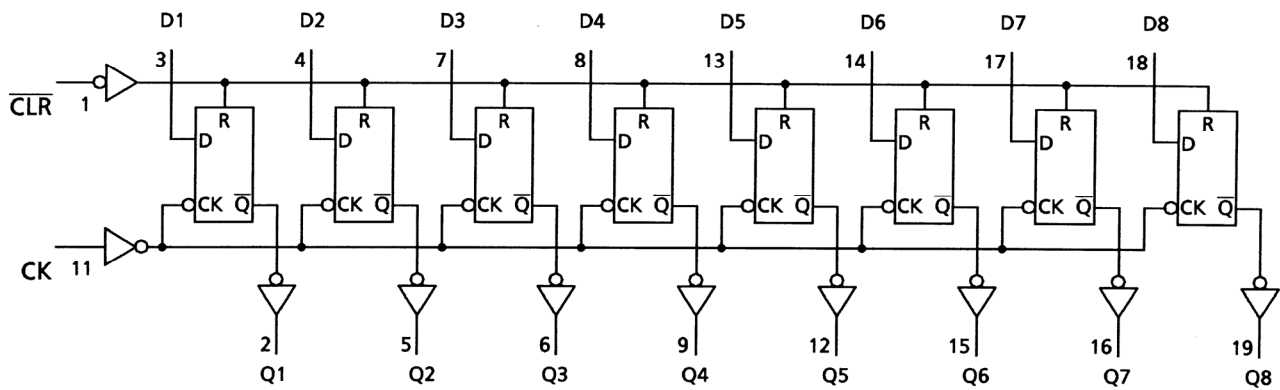


Truth Table

Inputs			Output	Function
CLR	D	CK	Q	
L	X	X	L	Clear
H	L		L	—
H	H		H	—
H	X		Q _n	No Change

X: Don't care

System Diagram



Absolute Maximum Ratings (Note 1)

Characteristics	Symbol	Rating	Unit
Supply voltage range	V_{CC}	$-0.5 \sim 7$	V
DC input voltage	V_{IN}	$-0.5 \sim V_{CC} + 0.5$	V
DC output voltage	V_{OUT}	$-0.5 \sim V_{CC} + 0.5$	V
Input diode current	I_{IK}	± 20	mA
Output diode current	I_{OK}	± 20	mA
DC output current	I_{OUT}	± 25	mA
DC V_{CC} /ground current	I_{CC}	± 50	mA
Power dissipation	P_D	500 (DIP) (Note 2)/180 (SOP)	mW
Storage temperature	T_{stg}	$-65 \sim 150$	$^{\circ}\text{C}$

Note 1: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Note 2: 500 mW in the range of $T_a = -40 \sim 65^{\circ}\text{C}$. From $T_a = 65$ to 85°C a derating factor of $-10 \text{ mW}/^{\circ}\text{C}$ shall be applied until 300 mW.

Recommended Operating Conditions (Note)

Characteristics	Symbol	Rating	Unit
Supply voltage	V_{CC}	$4.5 \sim 5.5$	V
Input voltage	V_{IN}	$0 \sim V_{CC}$	V
Output voltage	V_{OUT}	$0 \sim V_{CC}$	V
Operating temperature	T_{opr}	$-40 \sim 85$	$^{\circ}\text{C}$
Input rise and fall time	t_r, t_f	$0 \sim 500$	ns

Note: The recommended operating conditions are required to ensure the normal operation of the device. Unused inputs must be tied to either V_{CC} or GND.

Electrical Characteristics

DC Characteristics

Characteristics	Symbol	Test Condition		V _{CC} (V)	Ta = 25°C			Ta = -40~85°C		Unit
					Min	Typ.	Max	Min	Max	
High-level input voltage	V _{IH}	—		4.5~5.5	2.0	—	—	2.0	—	V
Low-level input voltage	V _{IL}	—		4.5~5.5	—	—	0.8	—	0.8	V
High-level output voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -20 μA	4.5	4.4	4.5	—	4.4	—	V
			I _{OH} = -4 mA	4.5	4.18	4.31	—	4.13	—	
Low-level output voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 20 μA	4.5	—	0.0	0.1	—	0.1	V
			I _{OL} = 4 mA	4.5	—	0.17	0.26	—	0.33	
Input leakage current	I _{IN}	V _{IN} = V _{CC} or GND		5.5	—	—	±0.1	—	±1.0	μA
Quiescent supply current	I _{CC}	V _{IN} = V _{CC} or GND		5.5	—	—	4.0	—	40.0	μA
	I _C	Per input: V _{IN} = 0.5 V or 2.4 V Other input: V _{CC} or GND		5.5	—	—	2.0	—	2.9	mA

Timing Requirements (input: $t_r = t_f = 6 \text{ ns}$)

Characteristics	Symbol	Test Condition	Ta = 25°C		Ta = -40 ~85°C	Unit
			V _{CC} (V)	Typ.	Limit	
Minimum pulse width (CK)	t_W (L)	—	4.5	—	15	ns
	t_W (H)		5.5	—	14	
Minimum pulse width ($\overline{\text{CLR}}$)	t_W (L)	—	4.5	—	15	ns
			5.5	—	14	
Minimum set-up time	t_s	—	4.5	—	10	ns
			5.5	—	10	
Minimum hold time	t_h	—	4.5	—	5	ns
			5.5	—	10	
Minimum removal time ($\overline{\text{CLR}}$)	t_{rem}	—	4.5	—	10	ns
			5.5	—	9	
Clock frequency	f	—	4.5	—	30	MHz
			5.5	—	35	

AC Characteristics ($C_L = 15 \text{ pF}$, $V_{CC} = 5 \text{ V}$, Ta = 25°C, input: $t_r = t_f = 6 \text{ ns}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Output transition time	t_{TLH}	—	—	4	8	ns
	t_{THL}					
Propagation delay time (CK-Q)	t_{pLH}	—	—	15	25	ns
	t_{pHL}					
Propagation delay time ($\overline{\text{CLR}}$ -Q)	t_{pHL}	—	—	18	28	ns
	t_{pHL}					
Maximum clock frequency	f_{max}	—	40	90	—	MHz

AC Characteristics ($C_L = 50 \text{ pF}$, input: $t_r = t_f = 6 \text{ ns}$)

Characteristics	Symbol	Test Condition	V_{CC} (V)	$T_a = 25^\circ\text{C}$			$T_a = -40 \sim 85^\circ\text{C}$		Unit
				Min	Typ.	Max	Min	Max	
Output transition time	t_{TLH}	—	4.5	—	9	15	—	19	ns
	t_{THL}		5.5	—	8	14	—	18	
Propagation delay time (CK-Q)	t_{pLH}	—	4.5	—	19	30	—	38	ns
	t_{pHL}		5.5	—	17	27	—	34	
Propagation delay time ($\overline{\text{CLR}}$ -Q)	t_{pLH}	—	4.5	—	22	32	—	40	ns
	t_{pHL}		5.5	—	18	29	—	36	
Maximum clock frequency	f_{max}	—	4.5	30	71	—	24	—	MHz
			5.5	35	81	—	28	—	
Input capacitance	C_{IN}	—	—	—	5	10	—	10	pF
Power dissipation capacitance	C_{PD} (Note)	—	—	—	29	—	—	—	pF

Note: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation:

$$I_{CC}(\text{opr}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/8 \text{ (per flip flop)}$$

And the total C_{PD} when n pcs. of flip flop operate can be gained by the following equation:

$$C_{PD}(\text{total}) = 18 + 11 \cdot n$$

DIP20-P-300-2.54A

The drawing includes three views of the connector:

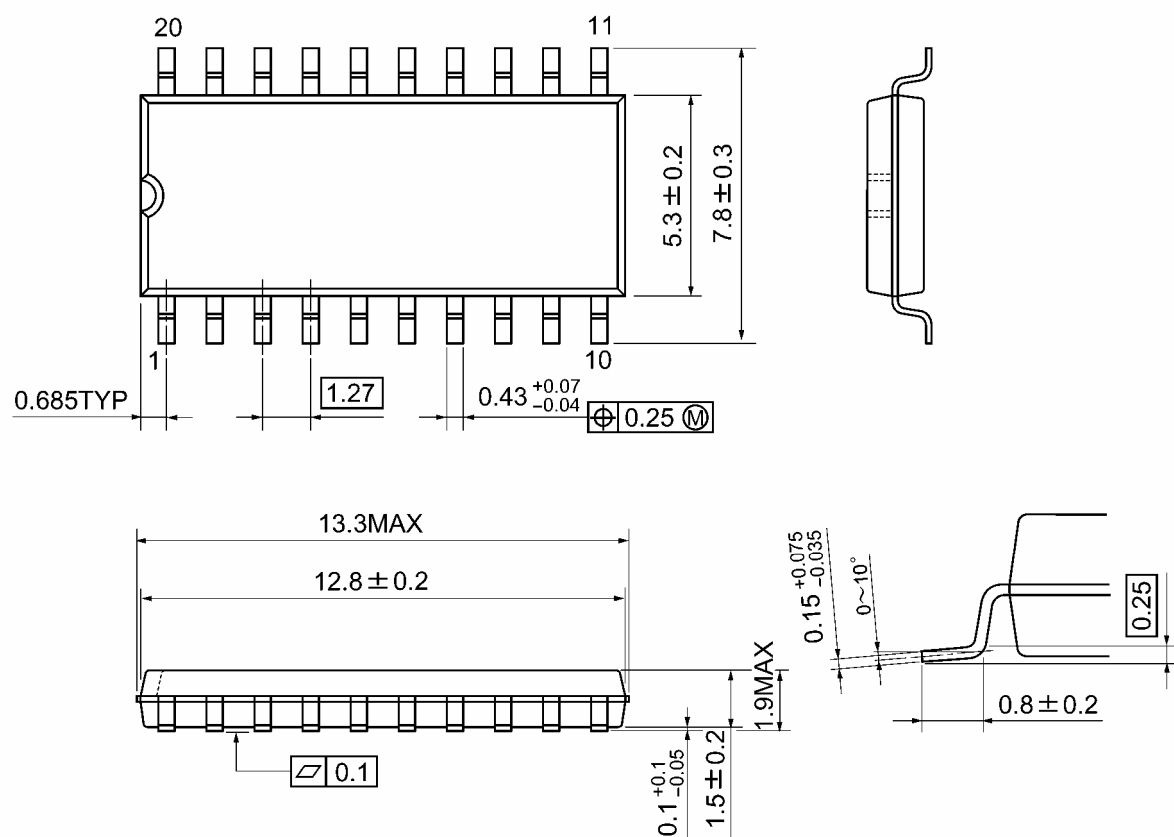
- Top View:** Shows a rectangular connector with 24 pins (12 on each long side). Pin 1 is at the bottom-left corner, and pin 11 is at the top-right corner. The width is 6.4 ± 0.2 .
- Side View:** Shows the profile of the connector. The height of the main body is 7.62 . The pins are angled at $0 \sim 15^\circ$ relative to the vertical. The pin thickness is $0.25^{+0.1}_{-0.05}$.
- Pin Detail View:** Shows the dimensions of the pins. The total length is 25.1 MAX . The length of the main body is 24.6 ± 0.2 . The pin pitch is 2.54 . The distance from the body to the first pin is 0.95 ± 0.1 . The pin height is 0.87 TYP . The pin thickness is 1.4 ± 0.1 . The distance from the body to the last pin is 0.5 ± 0.1 . The pin height is 0.51 MIN . The distance from the body to the last pin is 3.5 ± 0.2 . The distance from the body to the last pin is 4.15 ± 0.3 . The distance from the body to the last pin is 3.3 ± 0.3 . The distance from the body to the last pin is 0.25 (M) .

2006-06-01

Package Dimensions

SOP20-P-300-1.27A

Unit: mm

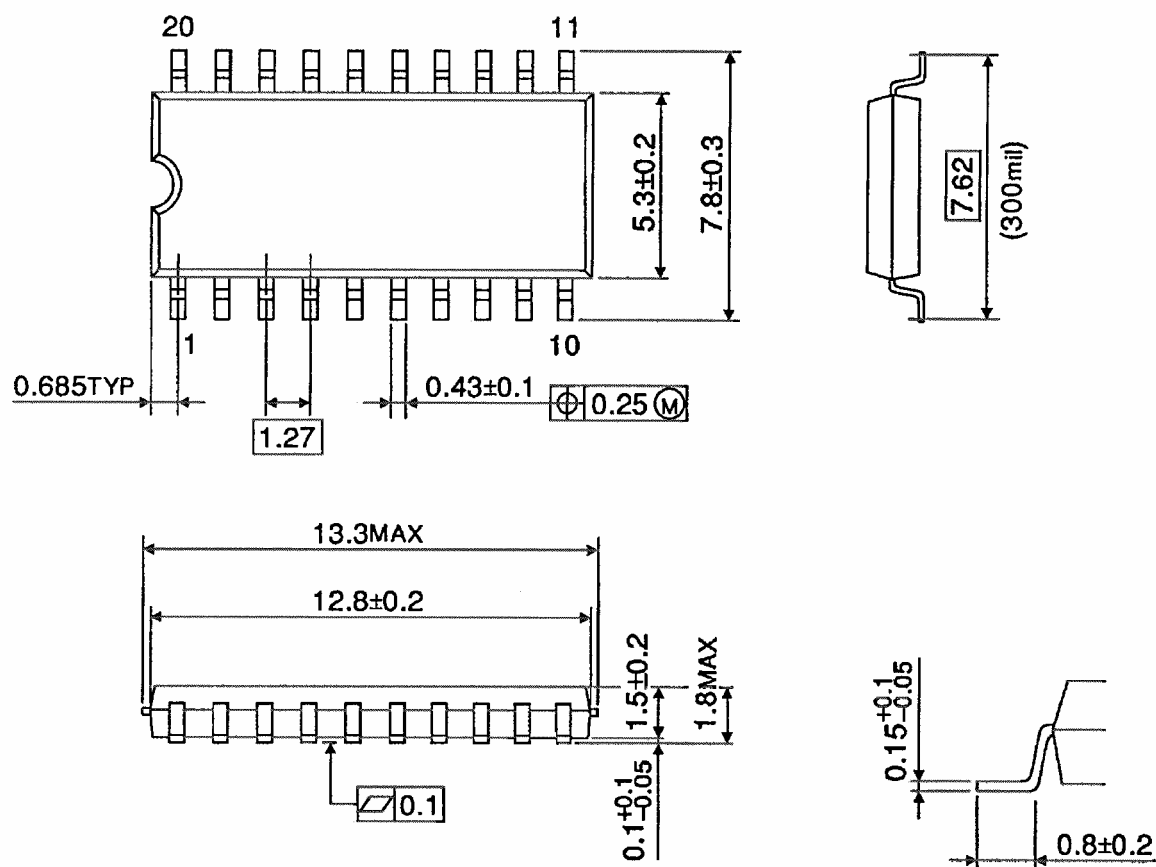


Weight: 0.22 g (typ.)

Package Dimensions

SOP20-P-300-1.27

Unit : mm

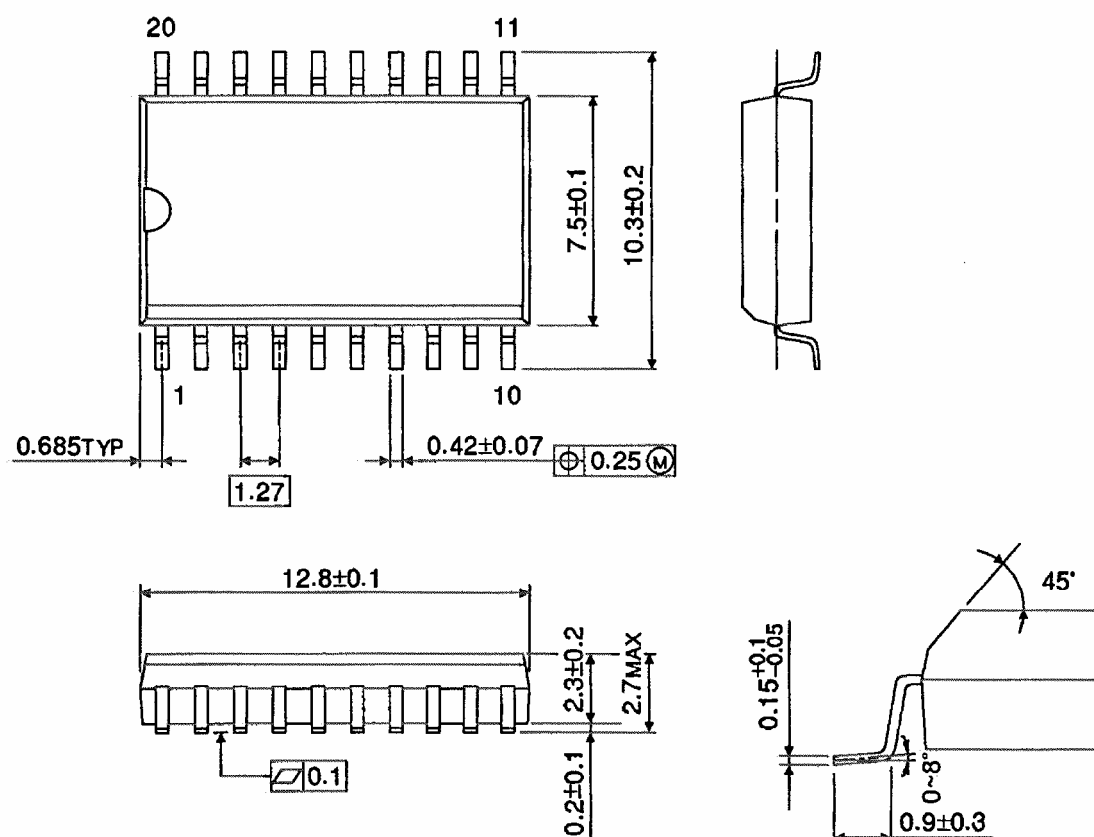


Weight: 0.22 g (typ.)

Package Dimensions (Note)

SOL20-P-300-1.27

Unit : mm



Note: This package is not available in Japan.

Weight: 0.46 g (typ.)

Note: Lead (Pb)-Free Packages

DIP20-P-300-2.54A SOP20-P-300-1.27A

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